Preliminary Data Sheet





Semiconductor Optical Amplifier

High Gain SemiNex SOA High Saturation Output Power Curved or Tilted Waveguide and Array 13xx and 15xx nm Custom Design and Waveguide available

- Applications

 FMCW LiDAR

 Telecom & Data Center

 Tunable Laser
- Spectroscopy
- Research

- Features

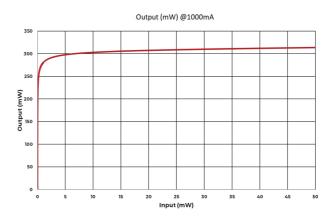
 High Gain

 High Saturation Power

 High Efficiency
- Cost Effective

SemiNex delivers SOAs with the highest gain and available saturation power at infrared wavelengths. When necessary we will further optimize the design of our InP SOA to meet our customers' specific optical and electrical performance needs. Single waveguide or arrays are tested to meet customer and market performance demands. Typical results and packaging options are shown. Contact SemiNex for additional details or performance demands.







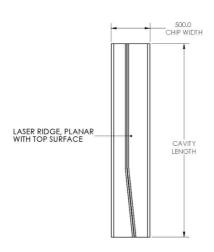


	Symbol	CHP-288	Units
Optical	Symbol	OTIF -200	Onits
Wavelength	λ _c	1310	nm (±20)
Output Power@1000mA	P _{out}	450	mW (±10%)
Aperture Width	AW	4	μm
Aperture Height	AH	1	μm
Spectral Width	δλ	85	nm @ 3dB
Gain @ Pin=10µW	G	30	dB
Beam Exit Angle	Θ_{EXT}	19.5	degree
Noise Figure	NF	6	db
Polarization Extinction Ratio	PER	18	dB
Fast Axis Div.	Θ_perp	30	deg FWHM
Slow Axis Div.	Θ parallel	16	deg FWHM
Front Facet Reflectivity		<0.1%	
Rear Face Reflectivity		<0.1%	
Waveguide		Curved	
Electrical			
Operating Voltage	V _{op}	2	V
Operating Current	I _{op}	1	A
Mechanical			
Chip Length	CL	2500	μm
Chip Width	W	500	μm
Weight		0.05	g
Operating Temp.**		-40 to 100	°C
Storage Temp.		-40 to 100	°C

^{**}Specified operating conditions are based on 20°C heat sink temperature. High temperature operation will reduce performance and MTTF.

**Specified values are based on the P-side down configuration and rated at a constant heat sink temperature of 20°C.

Unless otherwise indicated all values are nominal.



CHIP ATTRIBUTES		
WAVELENGTH	1550nm ±20nm	
APERTURE WIDTH	4μm ± 1μm	
CHIP WIDTH	0.500mm ±10µm	
THICKNESS	160µm±10µm	
CAVITY LENGTH	2.5mm ±10µm	

P-METAL				
MATERIAL	THICKNESS (nm)	TOLERANCE (nm)		
Ti	50	±10		
Pt	125	±25		
Au	250	+50		

N-METAL		
MATERIAL	THICKNESS (nm)	TOLERANCE (nm)
Ti	30	±10
Pt	125	±25
Au	400	+40

0.0 P-SIDE FULLY METALIZED SURFACE
160.0 N-SIDE FULLY METALIZED SURFACE

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